



YES-58TA Vapor Prime + Image Reversal Oven

Dual Function System for HMDS Application as well as Image Reversal

Specifications

Hardware	
Clean Room Compatibility	Class 10
Wafer Size	Up to 300mm
Capacity	12 cassettes 100mm wafers 8 cassettes 125mm or 150mm wafers 2 cassettes 200mm wafers 2 cassettes 300mm wafers
Batch Throughput	2 load/hr vacuum bake/vapor prime 1 load/hr image reversal
Operation Temperature	Ambient to 180 °C
Interior Chamber Dimensions	40.64 cm (W) x 45.72 cm (D) x 40.64 cm (H) (16" x 18" x 16")
Overall System Dimensions	73.5 cm (W) x 62.56 cm (D) x 88.27 cm (H) (28.94" x 24.63" x 34.75")
Chamber Material	316L stainless steel, aluminum door plate
Process Gas Inputs	1 N ₂ vent gas, 1 ammonia, 1 vapor flask
Cleanliness	<5 x 1 micron particles per 150 mm wafer
Nitrogen Consumption	16 SCF per process
Software	
Number of Recipes	8 process recipes
Range of Exposure Time	0-999999 seconds
Resolution of Timer Setting	1 second
Performance	
Temperature Uniformity	±5°C after stabilization period
Additional	
Power Requirements	188-253VAC, 50/60Hz, 10 amps



Contact Us

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +1 925-373-8353 (worldwide), 1-888-YES-3637 (US toll free), or visit us online at www.yieldengineering.com.

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